

**AMENDMENTS TO THE ABSTRACT**

Please replace the Abstract on page 61 with the following replacement paragraph:

-- The printed wiring board ~~of the invention~~ comprises, on at least one surface of an insulating film, a base metal layer and a conductive metal layer formed on the base metal layer, and is characterized in that in a section of the wiring board the bottom width of the conductive metal layer is smaller than the top width of the base metal layer. The circuit device ~~of the invention~~ comprises the printed wiring board and an electronic part mounted thereon. The process for producing a printed wiring board ~~of the invention~~ comprises bringing a base metal layer and a conductive metal layer into contact with an etching solution capable of dissolving the conductive metal to form a wiring pattern and then sequentially bringing the resultant into contact with a first treating solution capable of dissolving the metal for forming the base metal layer, a microetching solution capable of selectively dissolving the conductive metal and a second treating solution having a different chemical composition from the first treating solution in this order. ~~According to the present invention, migration from the base metal layer hardly occurs, and variation of a resistance value between terminals after application of a voltage is extremely small.~~--